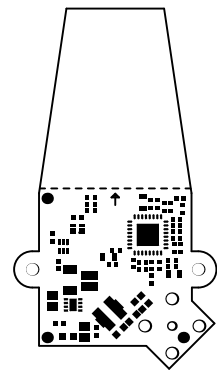
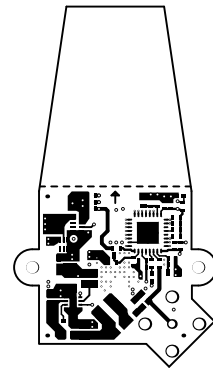


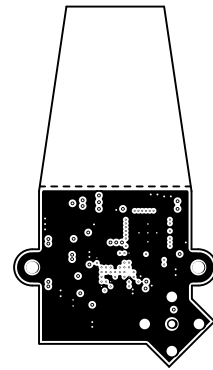
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01130	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 10/17/2017 1:47:05 PM	TEXAS INSTRUMENTS	



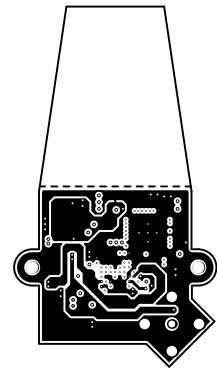
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01130	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 10/17/2017 1:47:06 PM	TEXAS INSTRUMENTS	



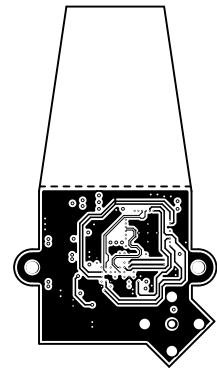
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01130	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Layer 1 - Top Layer			
PLOT NAME = Top Layer	GENERATED : 10/17/2017 1:47:07 PM	TEXAS INSTRUMENTS	



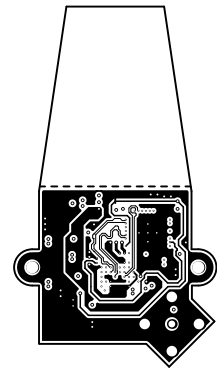
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01130	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Layer 2 - GND			
PLOT NAME = Signal Layer 1	GENERATED : 10/17/2017 1:47:08 PM	TEXAS INSTRUMENTS	



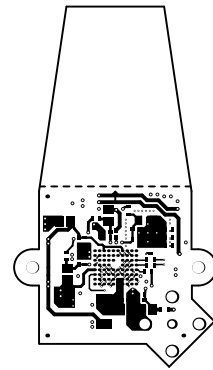
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01130	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Layer 5 - PWR			
PLOT NAME = Signal Layer 2	GENERATED : 10/17/2017 1:47:09 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01130	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Layer 3 - Signal			
PLOT NAME = Signal Layer 3	GENERATED : 10/17/2017 1:47:10 PM	TEXAS INSTRUMENTS	

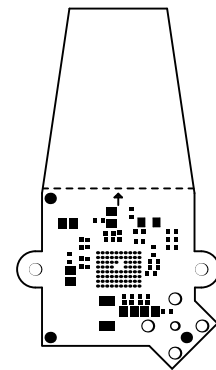


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01130	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Layer 4 - Signal			
PLOT NAME = Signal Layer 4	GENERATED : 10/17/2017 1:47:11 PM	TEXAS INSTRUMENTS	

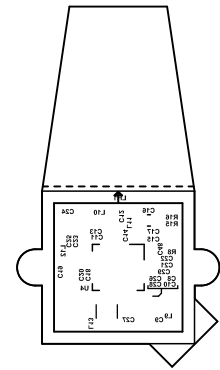


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01130	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Layer 6 - Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 10/17/2017 1:47:11 PM	TEXAS INSTRUMENTS	

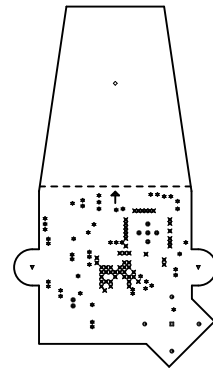




ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01130	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 10/17/2017 1:47:12 PM	TEXAS INSTRUMENTS	

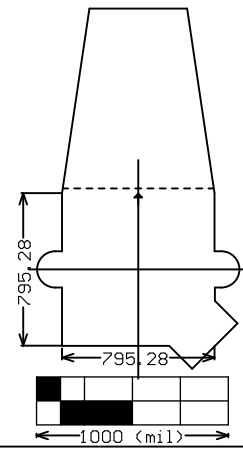


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01130	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 10/17/2017 1:47:13 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
▽	2	62.99mil (1.600mm)	NPTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
◇	1	280.00mil (7.112mm)	NPTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
✕	56	6.00mil (0.152mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
⊛	7	7.87mil (0.200mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
⊛	50	10.00mil (0.254mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
⊛	1	35.43mil (0.900mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
⊛	4	55.12mil (1.400mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
	121 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01130	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 10/17/2017 1:47:14 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01130	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 10/17/2017 1:47:16 PM	TEXAS INSTRUMENTS	

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